ABSTRACT

ADHESIVE TAPE

The present invention provides an adhesive tape comprising a flux-active compound having a carboxyl group and/or a phenolic hydroxyl group, a thermosetting resin and a film-forming resin. In the adhesive tape of the present invention, the thermosetting resin may be an epoxy resin and may contain a curing agent. The curing agent may be an imidazole compound and/or a phosphorous compound. The adhesive tape of the present invention can be used as an interlayer material for a circuit board and a multilayered flexible printed circuit board.

Fig. 1 accompanies the abstract